

P54/74FCT273/A/C (P54/74PCT273/A/C) OCTAL D FLIP-FLOP

FEATURES

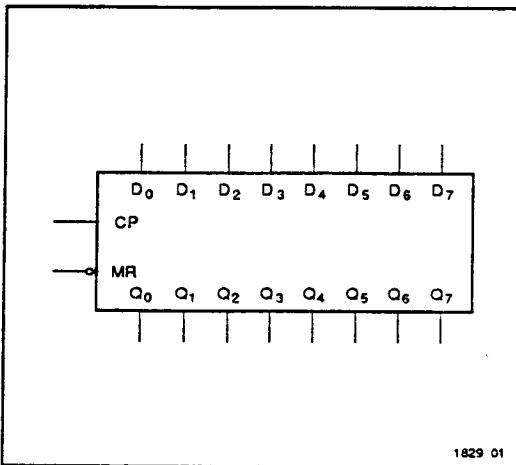
- Function, Pinout, and Drive Compatible with the FCT and F Logic
- FCT-C speed at 5.8ns max. (Com'l), FCT-A speed at 7.2ns max. (Com'l)
- CMOS V_{OH} Levels for Low Power Consumption — Typically 1/3 of FAST Bipolar Logic
- Edge-rate Control Circuitry for Significantly Improved Noise Characteristics
- ESD protection exceeds 2000V
- Inputs and Outputs Interface Directly with TTL, NMOS, and CMOS Devices
- Outputs Meet Levels Required for CMOS Static RAM Low Power Standby Mode
- 64 mA Sink Current (Com'l), 48 mA (MII), 15 mA Source Current (Com'l), 12 mA (MII)
- Edge Triggered D Flip-Flops
- 250MHz Typical Toggle Rate
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- Input Clamp Diode to Limit Bus Reflections
- Manufactured in 0.8 micron PACE Technology™

DESCRIPTION

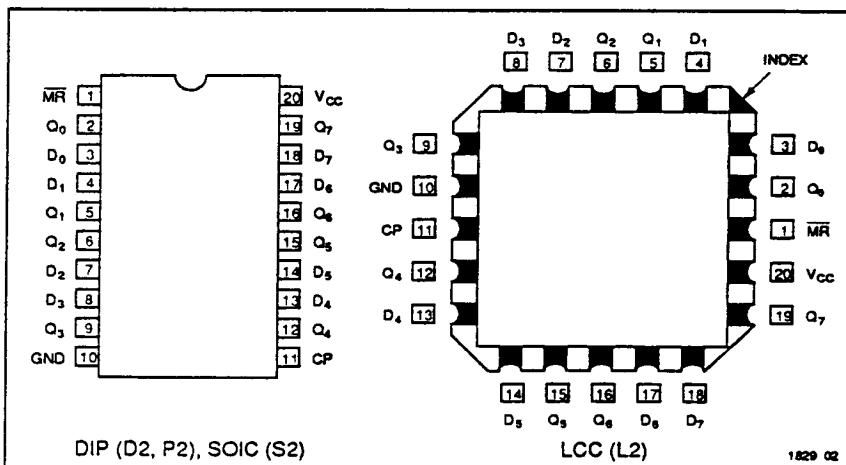
The 'FCT273 consists of eight edge triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered clock (CP) and master reset (MR) load and reset (clear) all flip-flops simultaneously. The 'FCT273 is an

edge triggered register. The state of each D input (one setup time before the low-to-high clock transition) is transferred to the corresponding flip-flop's Q output. All outputs will be forced low by a low voltage level on the MR input.

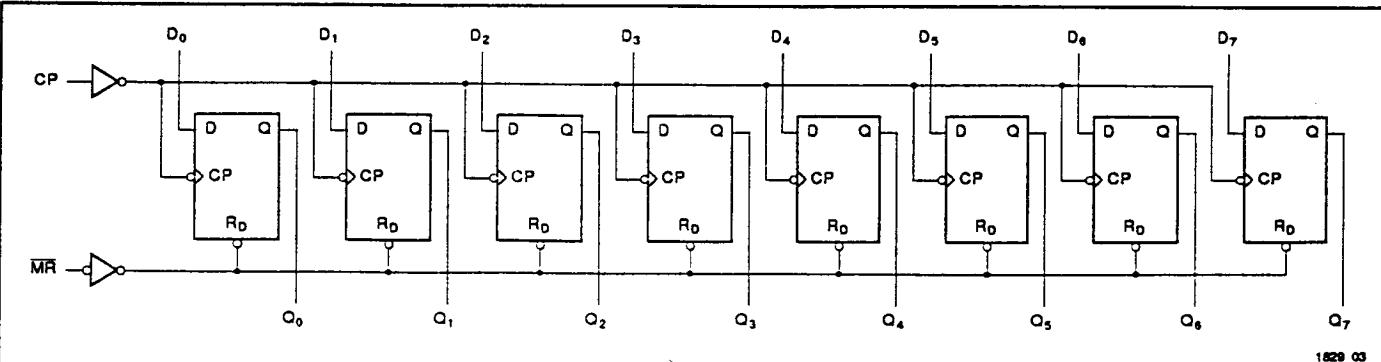
LOGIC SYMBOL



PIN CONFIGURATIONS



LOGIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{1,2}

Symbol	Parameter	Value	Unit
T _{STG}	Storage Temperature	-65 to +150	°C
T _A	Ambient Temperature Under Bias	-55 to +125	°C
V _{cc}	V _{cc} Potential to Ground	-0.5 to +7.0	V
I _{IN}	Input Current	-30 to +5.0	mA

Notes:

1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

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Symbol	Parameter	Value	Unit
I _{OUTPUT}	Current Applied to Output	100	mA
V _{IN}	Input Voltage	-0.5 to V _{cc} + 0.5	V
V _{OUT}	Voltage Applied to Output	-0.5 to V _{cc} + 0.5	V

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2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{cc} or ground.

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

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Supply Voltage (V _{cc})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

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DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter		Min	Typ ¹	Max	Units	V _{cc}	Conditions
V _{IH}	Input HIGH Voltage		2.0			V		
V _{IL}	Input LOW Voltage				0.8	V		
V _H	Hysteresis			0.35		V		All inputs
V _{CD}	Input clamp diode voltage				-1.2	V	MIN	I _{IN} = -18mA
V _{OH}	Output HIGH voltage	Military Commercial	2.4	3.3		V	MIN	I _{OH} = -12mA I _{OH} = -15mA
V _{OL}	Output LOW voltage	Military (TTL) Commercial (TTL)			0.5 0.5	V V	MIN MIN	I _{OL} = 32mA I _{OL} = 48mA
I _{IH}	Input HIGH Current				5	μA	MAX	V _{IN} = V _{cc}
I _{IL}	Input LOW Current				-5	μA	MAX	V _{IN} = GND
I _{IH}	Input HIGH Current ³				5	μA	MAX	V _{OUT} = 2.7V
I _{IL}	Input LOW Current ³				-5	μA	MAX	V _{OUT} = 0.5V
I _{OS}	Output short circuit ²		-60			mA	MAX	V _{OUT} = 0.0V
C _{IN}	Input capacitance ³			5	10	pF		All inputs
C _{OUT}	Output capacitance ³			9	12	pF		All outputs

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Notes:

1. Typical limits are at V_{cc} = 5.0V, T_A = +25°C ambient.
2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

3. This parameter is guaranteed but not tested.

DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ ¹	Max	Units	Conditions
I _{cc}	Quiescent Power Supply Current (CMOS inputs) Com'l Mil	0.003 0.003	0.3 0.5	mA mA	V _{cc} = MAX, V _{IN} ≤ 0.2V or V _{IN} ≥ V _{cc} - 0.2V, f = 0, Outputs Open
ΔI _{cc}	Quiescent Power Supply Current (TTL inputs)		2.0	mA	V _{cc} = MAX, V _{IN} = 3.4V ² , f = 0, Outputs Open
I _{ccD}	Dynamic Power Supply Current ³		0.25	mA/ mHz	V _{cc} = MAX, One Bit Toggling, 50% Duty Cycle, MR = V _{cc} , V _{IN} ≤ 0.2V or V _{IN} ≥ V _{cc} - 0.2V, Outputs Open
I _c	Total Power Supply Current ⁵		4.0	mA	V _{cc} = MAX, f _o = 10MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling at f ₁ = 5MHz, MR = V _{cc} and V _{IN} ≤ 0.2V or V _{IN} ≥ V _{cc} - 0.2V
			6.0	mA	V _{cc} = MAX, f _o = 10MHz, 50% Duty Cycle, Outputs Open, One Bit Toggling at f ₁ = 5MHz, MR = V _{cc} and V _{IN} = 3.4V or V _{IN} = GND
			7.8 ⁴	mA	V _{cc} = MAX, f _o = 10MHz, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f ₁ = 2.5MHz, MR = V _{cc} and V _{IN} ≤ 0.2V or V _{IN} ≥ V _{cc} - 0.2V
			16.8 ⁴	mA	V _{cc} = MAX, f _o = 10MHz, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at f ₁ = 2.5MHz, MR = V _{cc} and V _{IN} = 3.4V or V _{IN} = GND

Notes:

1. Typical values are at V_{cc} = 5.0V, +25°C ambient and maximum loading.
2. Per TTL driven input (V_{IN} = 3.4V); all other inputs at V_{cc} or GND.
3. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
4. Values for these conditions are examples of the I_{cc} formula. These limits are guaranteed but not tested.
5. I_c = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}
I_c = I_{cc} + ΔI_{cc}D_HN_T + I_{ccD}(f_o/2 + f₁N_I)
I_{cc} = Quiescent Current with CMOS input levels

ΔI_{cc} = Power Supply Current for a TTL High Input (V_{IN} = 3.4V)

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{ccD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_o = Clock Frequency for Register Devices (Zero for Non-Register Devices)

f₁ = Input Frequency

N_I = Number of Inputs at f₁

All currents are in milliamps and all frequencies are in megahertz.

MODE SELECT-FUNCTION TABLE

Operating Mode	Inputs			Output
	MR	CP	D _n	
Reset (clear)	L	X	X	L
Load '1'	H	⊜	h	H
Load '0'	H	⊜	l	L

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H = HIGH Voltage Level steady state

h = HIGH Voltage Level one setup time prior to LOW-to-HIGH clock transition

L = LOW Voltage Level steady state

l = LOW Voltage Level one setup time prior to the LOW-to-HIGH transition

X = Don't Care

⊜ = LOW-to-HIGH clock transition

AC CHARACTERISTICS

Symbol	Parameter	'FCT273				'FCT273A				'FCT273C				Units	Fig. No.		
		MIL		COM'L		MIL		COM'L		MIL		COM'L					
		Min. ¹	Max.	Min.	Max.	Min. ¹	Max.	Min.	Max.	Min. ¹	Max.	Min.	Max.				
t_{PLH} t_{PHL}	Propagation Delay Clock to Output	2.0	10.0	2.0	9.0	2.0	8.3	2.0	7.2	2.0	6.5	2.0	5.8	ns	1, 5		
t_{PLH} t_{PHL}	Propagation Delay \overline{MR} to Output	2.0	12.5	2.0	11.0	2.0	8.3	2.0	7.2	2.0	6.8	2.0	6.1	ns	1, 6		
$t_s(H)$ $t_s(L)$	Set-up Time HIGH or LOW D_n to CP	3.0	—	3.0	—	2.0	—	2.0	—	2.0	—	2.0	—	ns	4		
$t_h(H)$ $t_h(L)$	Hold Time HIGH or LOW D_n to CP	1.0	—	1.0	—	1.5	—	1.5	—	1.5	—	1.5	—	ns	4		
$t_w(H)$ $t_w(L)$	Clock Pulse Width ² HIGH or LOW	7.0	—	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	ns	5		
$t_w(H)$ $t_w(L)$	\overline{MR} Pulse Width LOW	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	6.0	—	ns	6		
t_{rec}	Recovery Time \overline{MR} to Clock	3.0	—	3.0	—	2.5	—	2.0	—	2.5	—	2.0	—	ns	6		

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Notes:

1. Minimum limits are guaranteed but not tested on Propagation Delays.
2. AC Characteristics guaranteed with $C_L = 50\text{pF}$ as shown in Figure 1.

ORDERING INFORMATION

PxxFCT Temp. Class	xxxx Device type	xx Package	x Processing			
				Blank	Commercial	
				M	Military Temperature	
				MB	MIL-STD-883, Class B	
				P	Plastic DIP	
				D	CERDIP	
				SO	Small Outline IC	
				L	Leadless Chip Carrier	
				273	OCTAL D FLIP-FLOP	
				273A	Fast OCTAL D FLIP-FLOP	
				273C	Ultra Fast OCTAL D FLIP-FLOP	
				74	Commercial	
				54	Military	

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